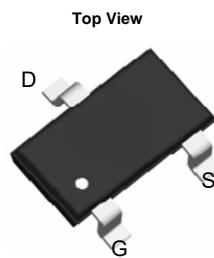
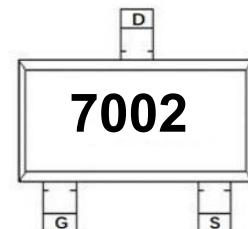


## Features

- 60V, 0.3A
- $R_{DS(ON)}$  Typ =  $1.7\ \Omega$  @  $V_{GS} = 10V$
- $R_{DS(ON)}$  Typ =  $2.0\ \Omega$  @  $V_{GS} = 4.5V$
- Advanced Trench Technology
- Excellent  $R_{DS(ON)}$  and Low Gate Charge
- Lead Free
- ESD Protected: 2KV

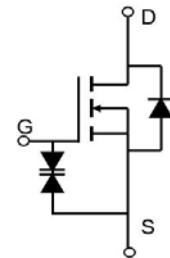


SOT23



## Application

- Battery Operated Systems
- Direct logic-level Interface:  
TTL/CMOS
- Solid-State Relays



### Absolute Maximum Ratings (@ $T_A = 25^\circ C$ unless otherwise specified)

Symbol	Parameter		Value	Units
$V_{DS}$	Drain-to-Source Voltage		60	V
$V_{GS}$	Gate-to-Source Voltage		$\pm 20$	V
$I_D$	Continuous Drain Current	$T_A = 25^\circ C$	0.3	A
		$T_A = 100^\circ C$	0.2	
$I_{DM}$	Pulsed Drain Current <sup>(1)</sup>		1.2	A
$P_D$	Power Dissipation	$T_A = 25^\circ C$	0.35	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient <sup>(2)</sup>		356	$^\circ C/W$
$T_J, T_{STG}$	Junction & Storage Temperature Range		-55 to 150	C

**Electrical Characteristics** ( $T_J = 25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	60	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 60\text{V}, V_{GS} = 0\text{V}$	-	-	1.0	$\mu\text{A}$
$I_{GSS}$	Gate-Body Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$	-	-	$\pm 10$	$\mu\text{A}$
<b>On Characteristics</b>						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1	1.6	2	V
$R_{DS(\text{ON})}$	Static Drain-Source ON-Resistance <sup>(3)</sup>	$V_{GS} = 10\text{V}, I_D = 0.3\text{A}$	-	1.7	2.1	$\Omega$
		$V_{GS} = 4.5\text{V}, I_D = 0.2\text{A}$	-	2.0	2.9	$\Omega$
			-	-	-	
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{GS} = 0\text{V}, V_{DS} = 25\text{V}, f = 1\text{MHz}$	-	28	-	pF
$C_{oss}$	Output Capacitance		-	11	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	4	-	pF
$Q_g$	Total Gate Charge	$V_{GS} = 0 \text{ to } 4.5\text{V}$ $V_{DS} = 10\text{V}, I_D = 0.3\text{A}$	-	1.7	-	nC
$Q_{gs}$	Gate Source Charge		-	0.3	-	nC
$Q_{gd}$	Gate Drain("Miller") Charge		-	0.6	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-On DelayTime	$V_{GS} = 10\text{V}, V_{DD} = 10\text{V}$ $I_D = 0.2\text{A}, R_{GEN} = 10\Omega$	-	2	-	ns
$t_r$	Turn-On Rise Time		-	15	-	ns
$t_{d(off)}$	Turn-Off DelayTime		-	7	-	ns
$t_f$	Turn-Off Fall Time		-	20	-	ns
<b>Drain-Source Diode Characteristics and Max Ratings</b>						
$I_s$	Maximum Continuous Drain to Source Diode Forward Current	-	-	0.3	A	
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	1.2	A	
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS} = 0\text{V}, I_s = 0.3\text{A}$	-	-	1.2	V

Notes:

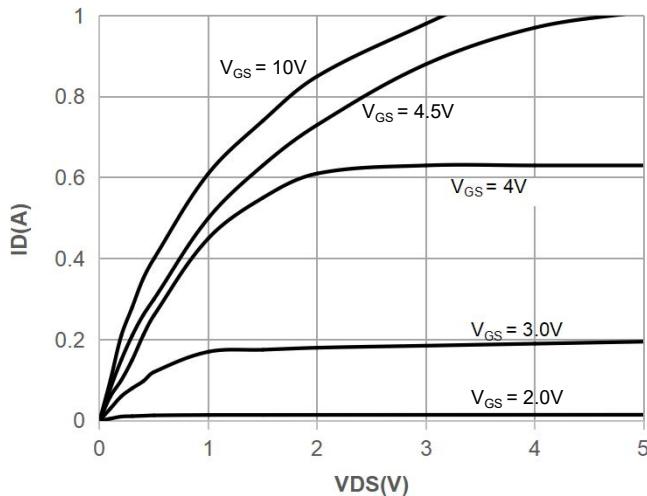
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

2.  $R_{\theta JA}$  is measured with the device mounted on a 1inch<sup>2</sup> pad of 2oz copper FR4 PCB

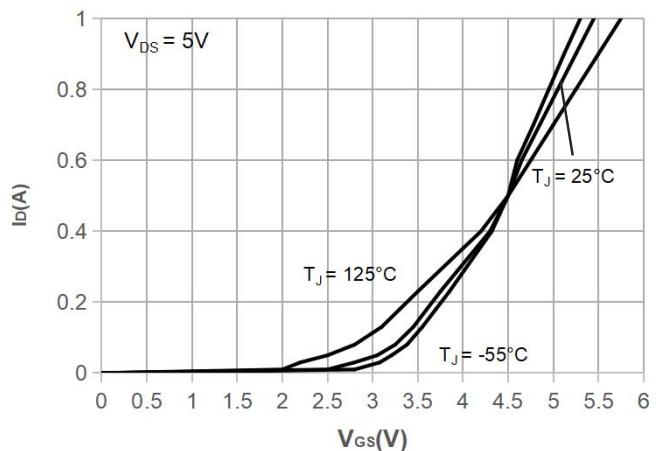
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 0.5\%$ .

## Typical Performance Characteristics

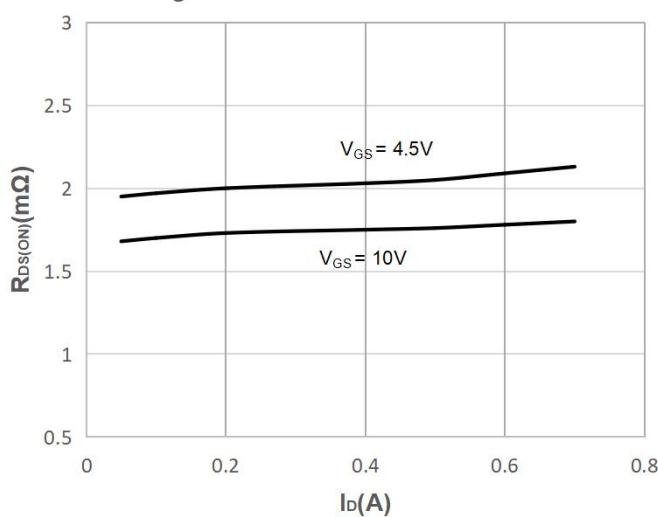
**Figure 1: Output Characteristics**



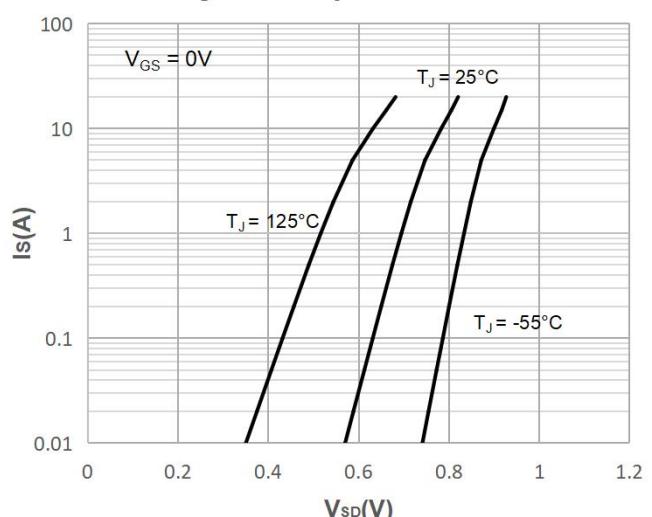
**Figure 2: Typical Transfer Characteristics**



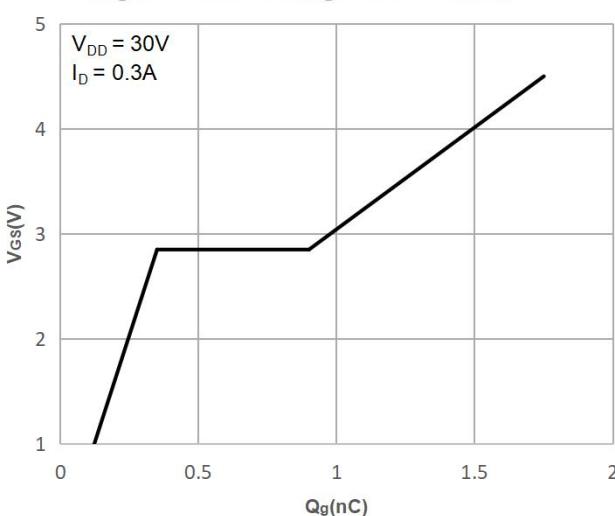
**Figure 3: On-resistance vs. Drain Current**



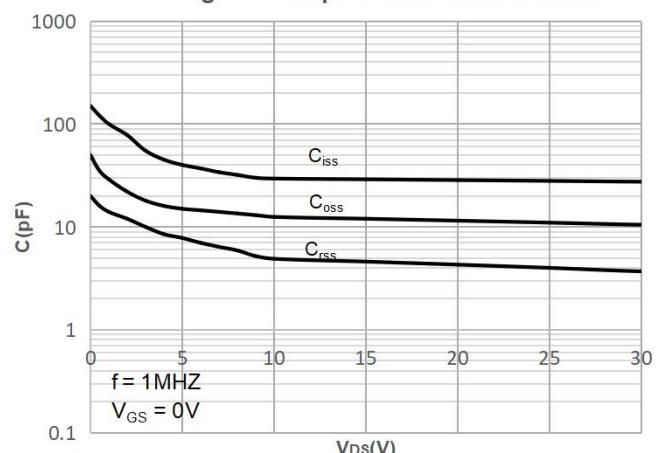
**Figure 4: Body Diode Characteristics**



**Figure 5: Gate Charge Characteristics**

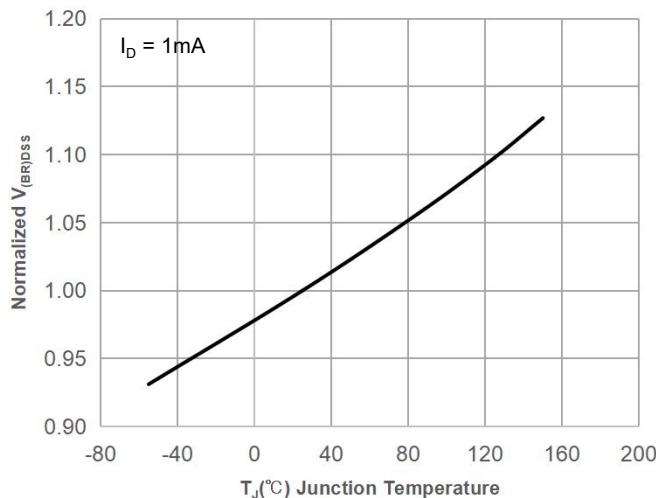


**Figure 6: Capacitance Characteristics**

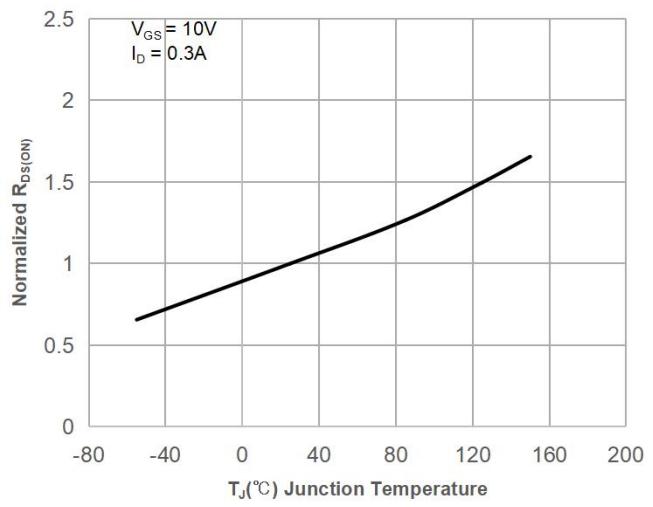


## Typical Performance Characteristics

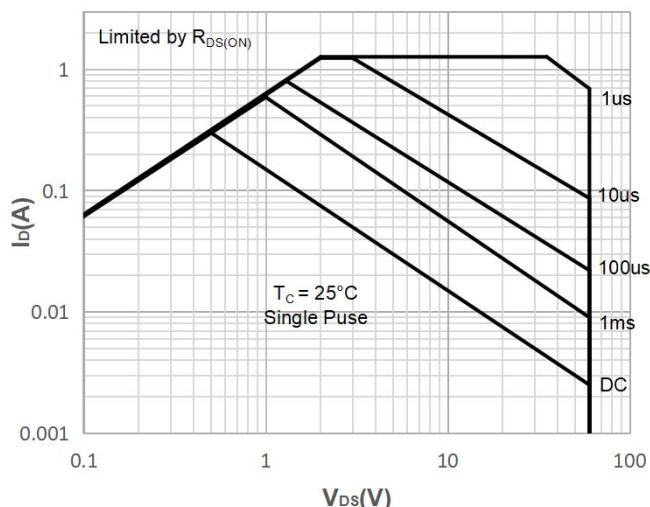
**Figure 7: Normalized Breakdown voltage vs. Junction Temperature**



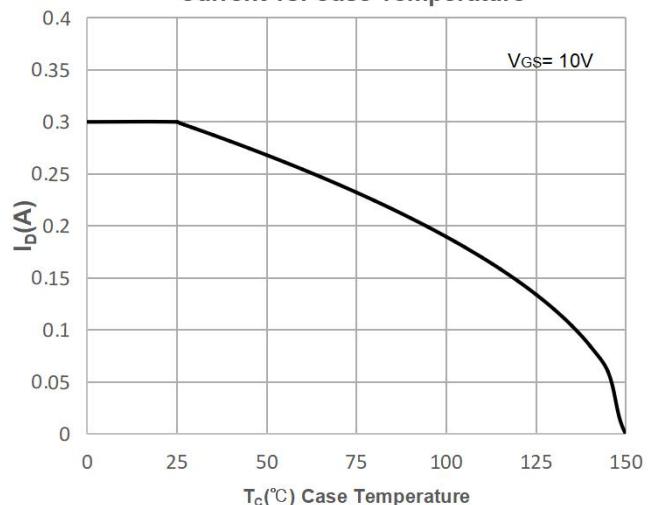
**Figure 8: Normalized on Resistance vs. Junction Temperature**



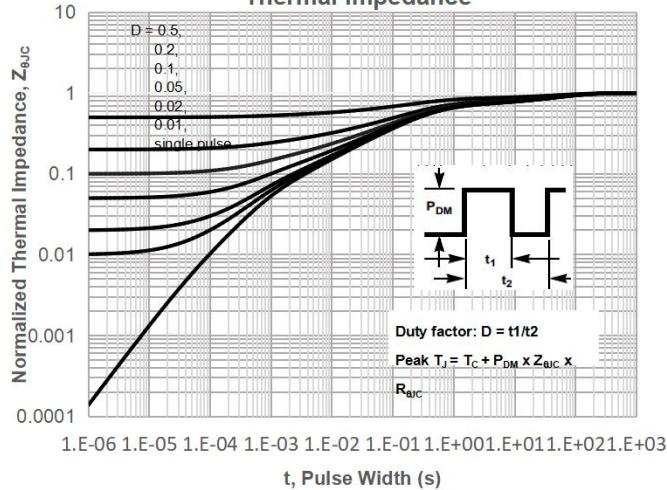
**Figure 9: Maximum Safe Operating Area**



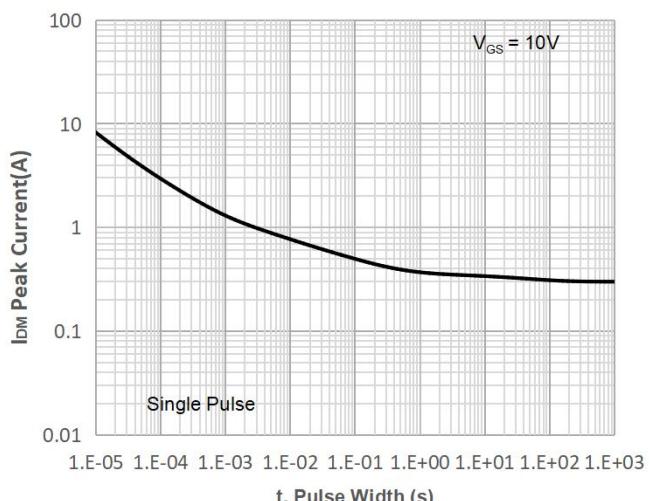
**Figure 10: Maximum Continuous Drain Current vs. Case Temperature**



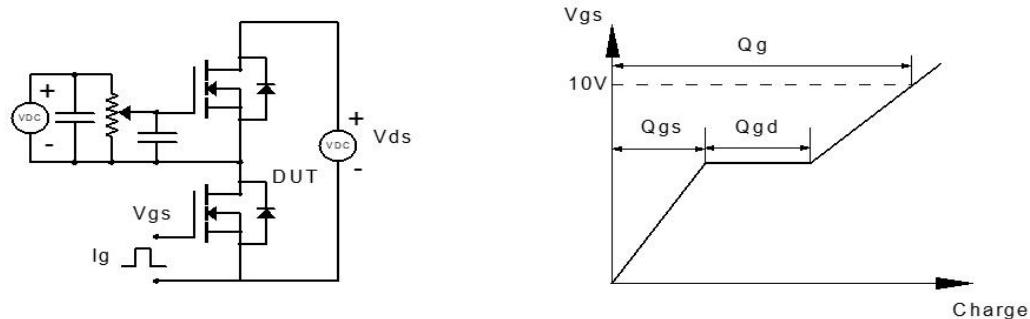
**Figure 11: Normalized Maximum Transient Thermal Impedance**



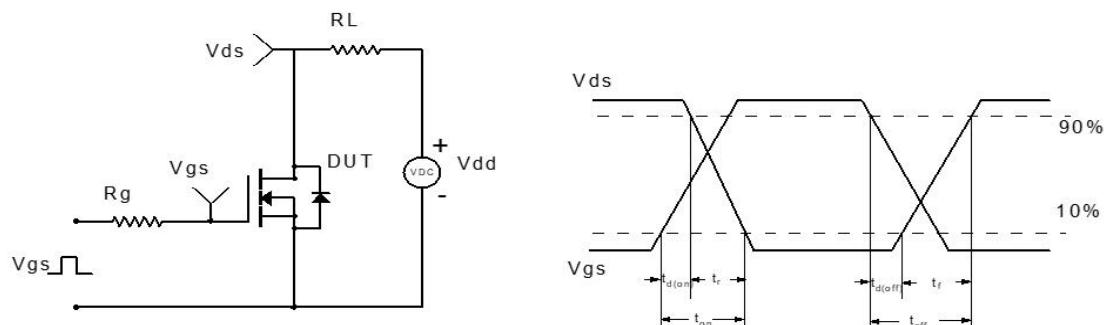
**Figure 12: Peak Current Capacity**



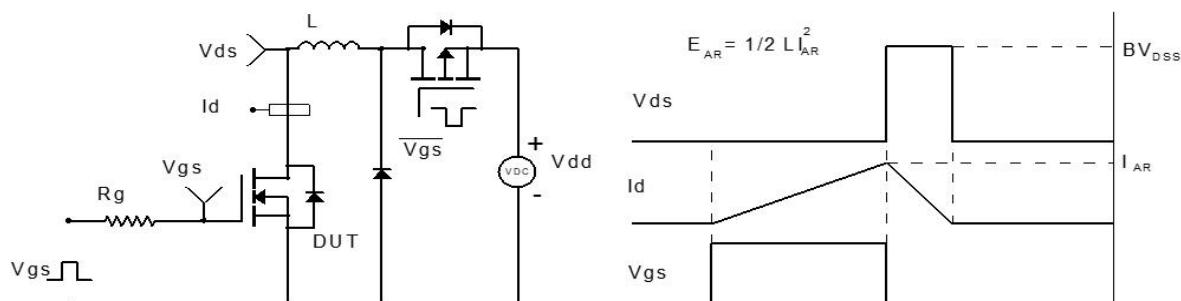
## Test Circuit



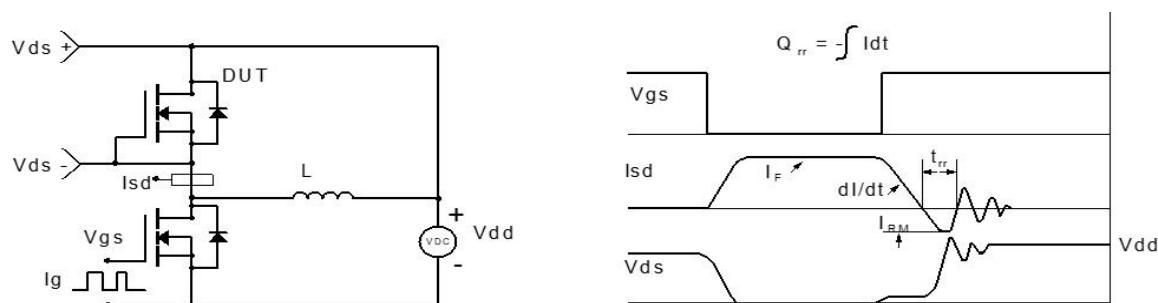
**Figure 1: Gate Charge Test Circuit & Waveform**



**Figure 2: Resistive Switching Test Circuit & Waveform**

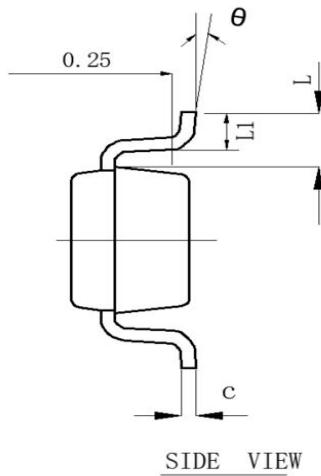
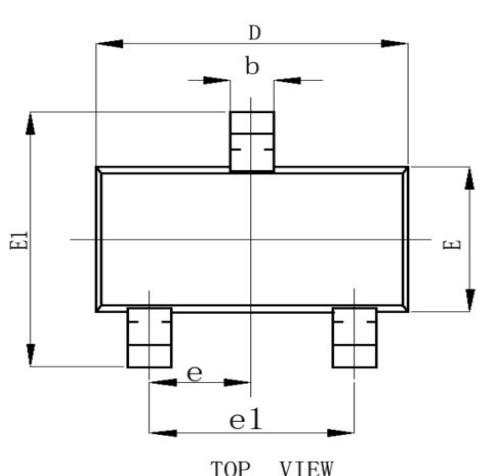


**Figure 3: Unclamped Inductive Switching Test Circuit & Waveform**



**Figure 4: Diode Recovery Test Circuit & Waveform**

## Package Mechanical Data(SOT-23)



COMMON DIMENSIONS In Millimeters		
SYMBOL	MIN	MAX
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
L	0.550 REF.	
$\theta$	0°	8°
L1	0.300	0.500
e	0.950 TYP.	
e1	1.800	2.000

